



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Harpreet S. Sandhu et al.

Title: METHOD FOR FORMING A METALLIZATION LAYER

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Examiner: Dung Le

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Commissioner for Patents

Attn: MAIL STOP ISSUE FEE

P.O. Box 1450

Alexandria, VA 22313-1450

**Notice of Allowance Date:**

January 25, 2007

We are transmitting herewith the attached:

- ☒ Authorization to charge Deposit Account 19-0743 in the amount of \$1400.00 to cover the Large Entity Issue Fee Payment.
- ☒ Authorization to charge Deposit Account 19-0743 in the amount of \$300.00 to cover the Publication Fee Payment.
- ☒ Issue Fee Transmittal (Form PTOL-85).
- ☒ Communication Re: Fee Address (1 page).
- ☒ Amendment Under 37 C.F.R. § 1.312 (8 pages).
- ☒ A return postcard.

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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number: 21186

By

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MLB/cmb

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Attn – MAIL STOP ISSUE FEE, P.O. Box 1450, Alexandria, VA 22313-1450, on this 10 day of April, 2007.

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